

# Chip Scale Review®

ChipScaleReview.com

The Future of Semiconductor Packaging

## 2017 Editorial Calendar

(Editorial close date: 11/20)

January • February

\* indicates show distribution

Industry forecast

Future of packaging with silicon photonics

FOWLP technology trends

Cu pillars for 3D stacking

Electroplating for packaging applications

Electronic assembly reliability

Metrology for lithography applications

Package integration drives RF test complexity

High frequency test sockets

- **SEMI European 3D Summit**  
Grenoble, France (Jan 23-25)
- **SMTA Pan Pac Microelectronics Symposium \***  
Kauai, Hawaii (Feb 6-9)
- **SEMICON Korea**  
Seoul, Korea (Feb 8-10)
- **APEX Expo**  
San Diego, CA (Feb 14-16)
- **ISS Europe**  
Munich, Germany (March 5-8)
- **BiTS Workshop\***  
**Mesa, AZ (March 5-8)**
- **IMAPS DPC\***  
Fountain Hills, AZ (March 6-9)
- **SEMICON China\***  
Shanghai, China (March 14-16)\*

**Ad Space Close Jan 6 - Ad Materials Close Jan 11**

(Editorial close date: 1/6)

March • April

\* indicates show distribution

Challenges & opportunities for OSATS

Hi-accuracy metrology

Glass-based SiP solutions

Die attach solutions

Electronic materials

Embedded & fan-out packaging

Testing of MEMS / sensors in HVM

Wafer-level test

Core capabilities of a thermocompression bonder

Additive manufacturing for packaging applications

- **2017 ICEP**  
Tendo, Japan (April 19-22)
- **SEMICON SE Asia**  
Penang, Malaysia (Apr 25-27)
- **MEMS & Sensors Technical Congress**  
Stanford, CA (May 10-11)
- **ECTC \***  
Lake Buena Vista, FL (May 30- June 2)

**Ad Space Close Feb 17 - Materials Close Feb 24**

(Editorial close date: 3/10)

May • June

\* indicates show distribution

Recent advances & new trends in semiconductor packaging

WLP market update

HD FO for HP & RF applications

Chip scale packaging for LED applications

Wirebond BGAs

KGD testing

Thin wafer handling

3D technology failure analysis

Feature: 50 years of CEA-Leti – past, present, future

- **IEEE/SW Test Workshop (SWTW)**  
San Diego, CA (June 5-8)
- **Meptec MEMS & Sensors Symposium**  
San Jose, CA (June 6)
- **European SiPAT Networking Day\***  
Porto, Portugal (June 22)
- **IMAPS SiP 2017\***  
Sonoma, CA (June 27-29)
- **Sensors Expo & Conference**  
San Jose, CA (June 27-29)
- **SEMICON West \***  
San Francisco, CA (July 12-14)

**Ad Space Close April 21 - Ad Materials Close April 28**

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Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

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